

L Number	Hits	Search Text	DB	Time stamp
1	3973	324/765-769.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 11:43
8	269	324/765-769.ccls. and spring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 11:43
15	199	(324/765-769.ccls. and spring) and (ball bead bump lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 11:44
22	7542	(ball bump bead) near8 (contact\$3 connect\$3) near8 spring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 13:34
29	127	((ball bump bead) near8 (contact\$3 connect\$3) near8 spring) and BGA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 13:33
36	2230	(ball bump bead) near3 (contact\$3 connect\$3) near3 spring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:53
43	270338	(opening hole via socket) near20 spring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:17
50	945	((ball bump bead) near3 (contact\$3 connect\$3) near3 spring) and ((opening hole via socket) near20 spring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:20
57	282	((ball bump bead) near3 (contact\$3 connect\$3) near3 spring) near20 (portion part)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:27
64	24	((ball bump bead) near3 (contact\$3 connect\$3) near3 spring) and ((opening hole via socket) near20 spring)) and bga	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:28
71	430	(ball bump bead) near3 (contact\$3 connect\$3) near3 (coil helix helical spiral)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:55
78	8	((ball bump bead) near3 (contact\$3 connect\$3) near3 (coil helix helical spiral)) and bga	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 15:54

85	3	5854558.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:57
92	2	6229320.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:58
99	11947	fill\$3 near3 (hole via groove socket) near10 (conduct\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 16:26
106	169	((opening hole via socket) near20 spring) and (fill\$3 near3 (hole via groove socket) near10 (conduct\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 16:13
113	23	((opening hole via socket) near20 spring) same (fill\$3 near3 (hole via groove socket) near10 (conduct\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 16:11
120	0	((ball bump bead) near3 (contact\$3 connect\$3) near3 (coil helix helical spiral)) same (fill\$3 near3 (hole via groove socket) near10 (conduct\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 16:12
127	1	((ball bump bead) near3 (contact\$3 connect\$3) near3 (coil helix helical spiral)) and (fill\$3 near3 (hole via groove socket) near10 (conduct\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 16:12
134	29	((opening hole via socket) near20 spring) and (fill\$3 near3 (hole via groove socket) near10 (conduct\$3))) and (PCB PWB BGA)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 16:15
141	3	5,366,380.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 16:15
148	161	(hole via groove socket) near10 (conduct\$3 solder paste) near10 ((hold\$3 bond\$3) near3 (spring coil helix helical spiral))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 16:56